

ICEP-HBS 2026 Program Overview

HBS		
April 14 (Tue)		
Room A (Phoenix)		
Greeting	13:00	TBD
Speaker 1	13:10	
Speaker 2	13:40	
Speaker 3	14:10	
Speaker 4	14:40	
	15:10	
Break		
Speaker 5	15:30	TBD
Speaker 6	16:00	
Speaker 7	16:30	
	17:00	

April 15 (Wed)						
	Room A (Phoenix)	Room B (Himawari)	Room C (Daria1)	Room D (Daria2)	Room E (Cosmos)	Room F (Ran)
9:00	15FA1 INEMI	15WB1 EPTC	15WC1 AdvancedPackaging-1	15WD1 Inteconect-1	15WE1 Material-1	15WF1 Emerging Technologies-1
10:40			Fanout Packing-1	Hybrid Bonding Process		
10:55	15WA2 MEF PKG	15WB2 IMAPS	15WC2 AdvancedPackaging-2	15WD2 Inteconect-2	15WE2 Material-2	15WF2 Emerging Technologies-2
12:35	3	3	Fanout Packing-2	Solder/Intermetallic		
12:35	Lunch					
12:55 13:25	Luncheon Talk					
13:35	Poster Core session					
14:50						
	Break 10min					
15:00	Award Ceremony					
	Break 10min					
15:40 16:40	Keynote I (Micron)					
16:40 17:40	Keynote II (TBD)					
17:40	Introduction of ICEP2027					
17:45	Participants will travel to the party venue by charter bus.					
18:15 20:15	Welcome reception(Grand Prince Hotel Hiroshima)					

ICEP-HBS 2026 Program Overview

April 16 (Thu)						
8:30 9:15	KeynotⅢ(DISCO)					
	Room A (Phoenix)	Room B (Himawari)	Room C (Daria1)	Room D (Daria2)	Room E (Cosmos)	Room F (Ran)
9:30	16TA1	16TB1	16TC1	16TD1	16TE1	16TF1
	Glass-PKG-1	ISMP-1	AdvancedPackaging-3	Inteconect-3	Material-3	ThermalManagement-1
11:10			Ceramic Solution	Cu-Cu Bonding		
11:25	16TA2	16TB2	16TC2	16TD2	16TE2	16TF2
	Glass-PKG-2	ISMP-2	AdvancedPackaging-4	Inteconect-4	Material-4	ThermalManagement-2
13:05			Direct Bonding	Interconnect		
13:05 13:55						
	Room A (Phoenix)	Room B (Himawari)	Room C (Daria1)	Room D (Daria2)	Room E (Cosmos)	Room F (Ran)
13:55	16TA3	16TB3	16TC3	16TD3	16TE3	16TF3
	PLP	SMTA	AdvancedPackaging-5	DMR-E	Material-5	ThermalManagement-3
15:35			Process Development-1			
15:50	16TA4	16TB4	16TC4	16TD4	16TE4	16TF4
	HIR	Setouchi	AdvancedPackaging-6	DMR-M1	Material-6	ThermalManagement-4
17:30			Process Development-2	Mechanical simulation-1		
17:30 18:45	Poster Core session					
18:45 19:30	Sponsor's exhibition party (Hiroshima International Conference Center)					

ICEP-HBS 2026 Program Overview

April 17 (Fri)						
8:30	KeynotIV (IBM)					
9:15						
9:15	KeynotV (imec)					
10:00						
	Room A (Phoenix)	Room B (Himawari)	Room C (Daria1)	Room D (Daria2)	Room E (Cosmos)	Room F (Ran)
10:15	17FA1	17FB1	17FC1	17FD1	17FE1	17FF1
11:55	IMPACT	Printed Electronics	AdvancedPackaging-7	DMR-M2	High-SpeedWireless	ThermalManagement-5
			Hybrid Bonding 1	Mechanical simulation-2		
11:55						
12:45						
	Room A (Phoenix)	Room B (Himawari)	Room C (Daria1)	Room D (Daria2)	Room E (Cosmos)	Room F (Ran)
12:45	17FA2	17FB2	17FC2	17FD2	17FE2	17FF2
	Glass-PKG3	ICEPT	AdvancedPackaging-8	DMR-M3	Process-1	Powe Electronics-1
14:25			Hybrid Bonding 2	Reliability -1	Material Processing	
14:40	17FA3	17FB3	17FC3	17FD3	17FE3	17FF3
	Glass-PKG-4	Co-packaged OPT	AdvancedPackaging-9	DMR-M4	Process-2	Powe Electronics-2
16:20			Hybrid Bonding 3	Reliability -2	Measarement Method	
16:35			17FC4	17FD4	17FE4	17FF4
			AdvancedPackaging-10	DMR-M5	Optoelectronics	Powe Electronics-3
18:15			TSV	Reliability -3		